


# **Metallization: Cost Reduction and Performance Optimization for the Key Consumable of Solar Cell Production**

Solamet Electronic Materials

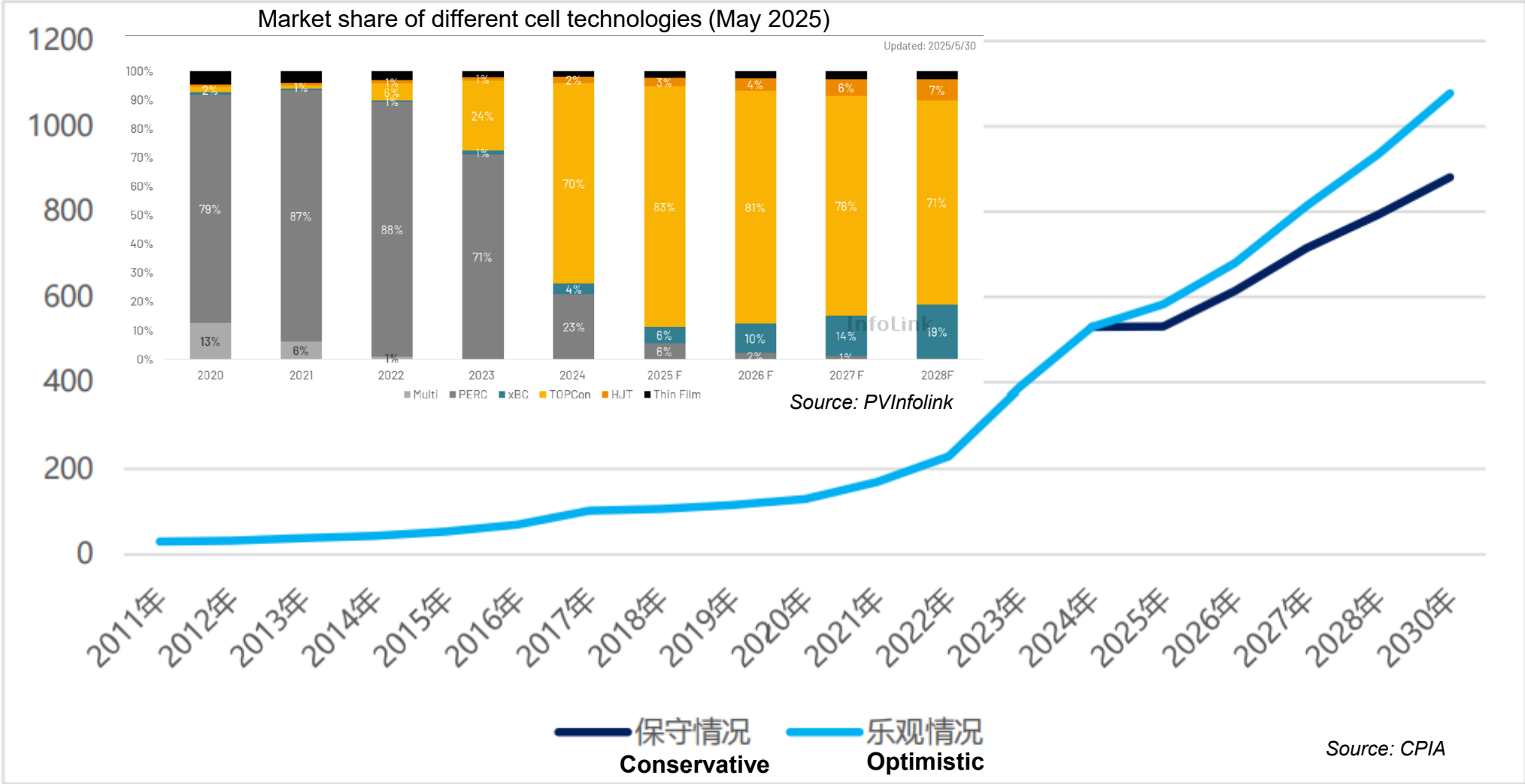
Dr. QJ Guo, CTO

2025-09-08

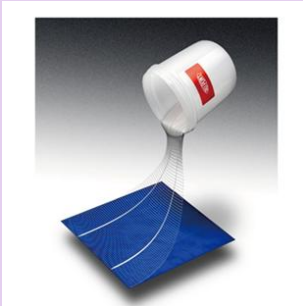
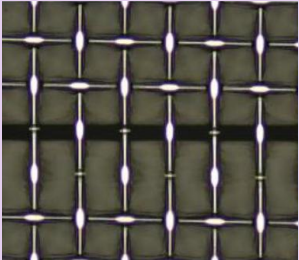


# Overview of the PV market and solar cell technologies

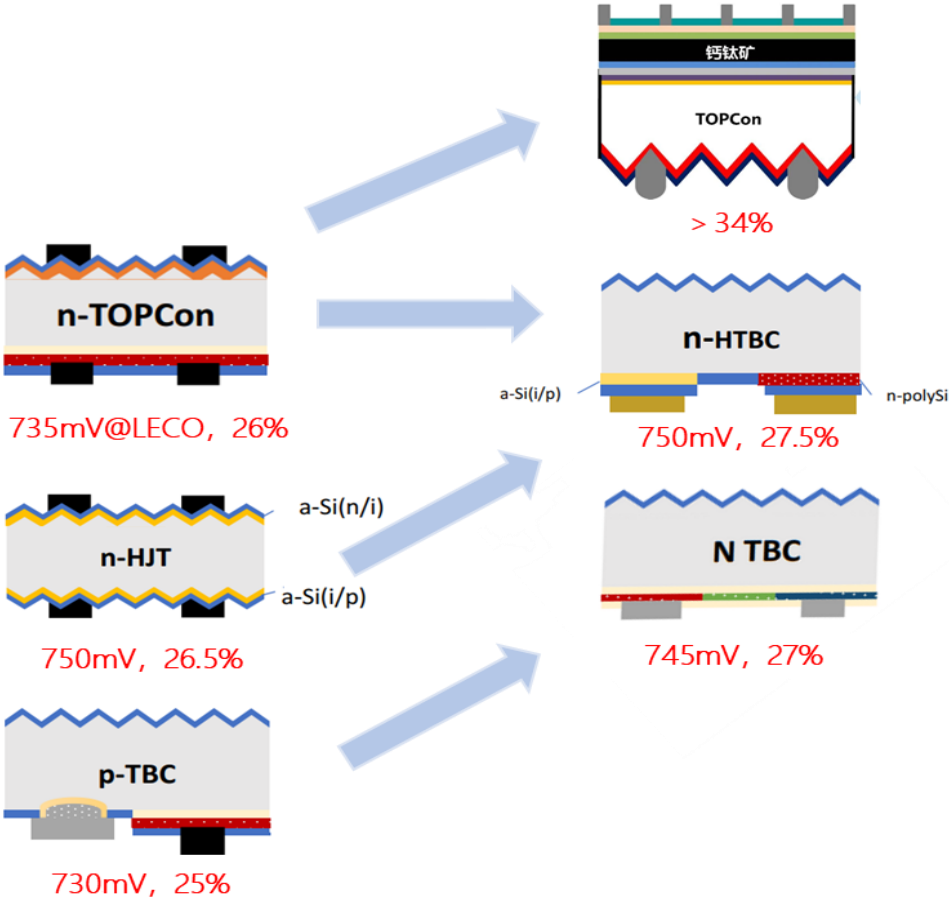
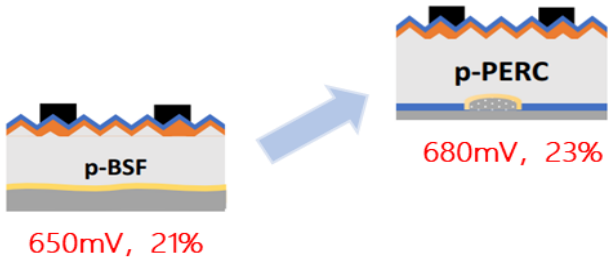
High efficiency n-TOPCon solar cells is mainstream



# Metallization is key to industrialization of higher efficiency solar cells



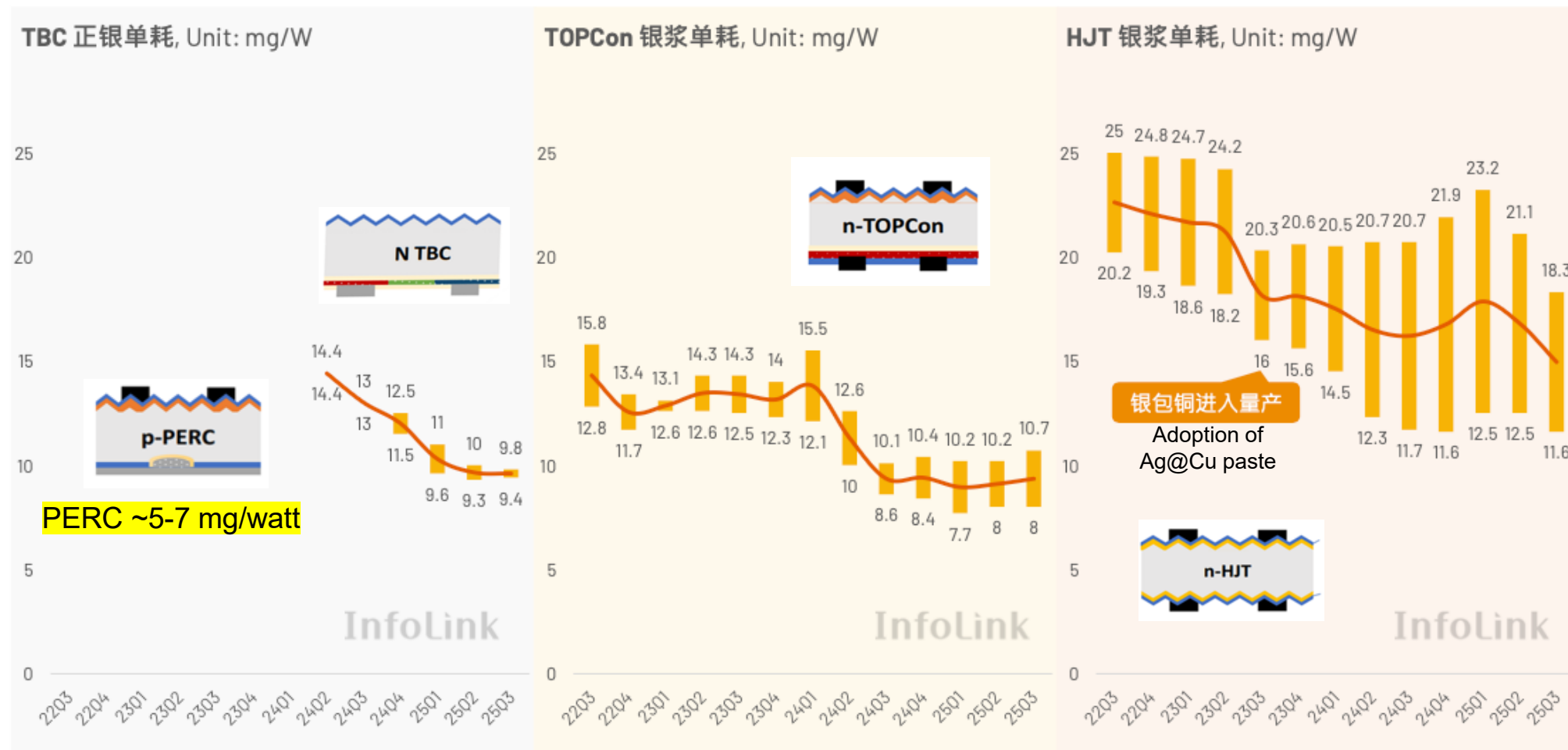
Advancements in paste and screen technologies have been able to continuously enable improvements in cell efficiency and production cost



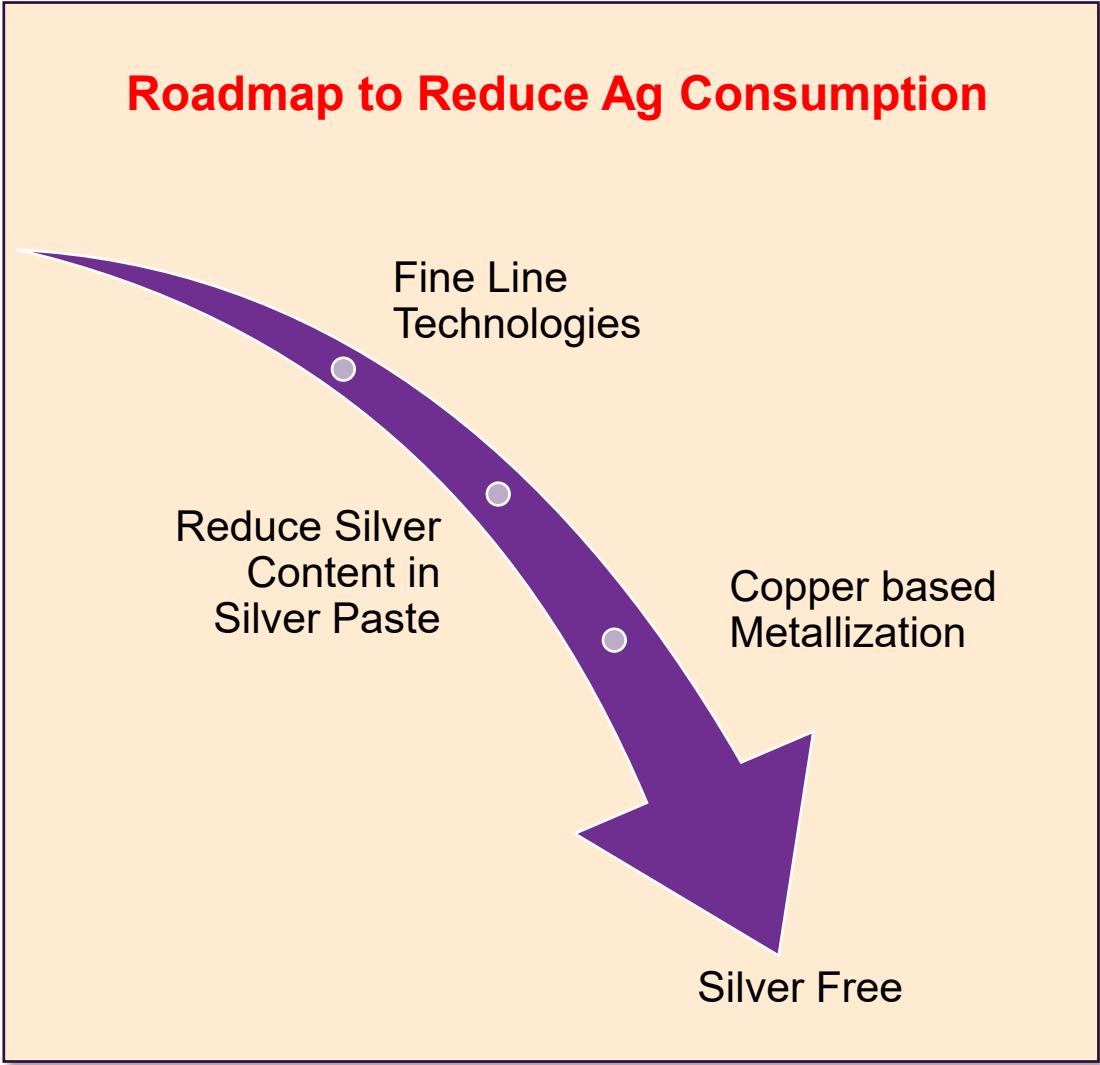
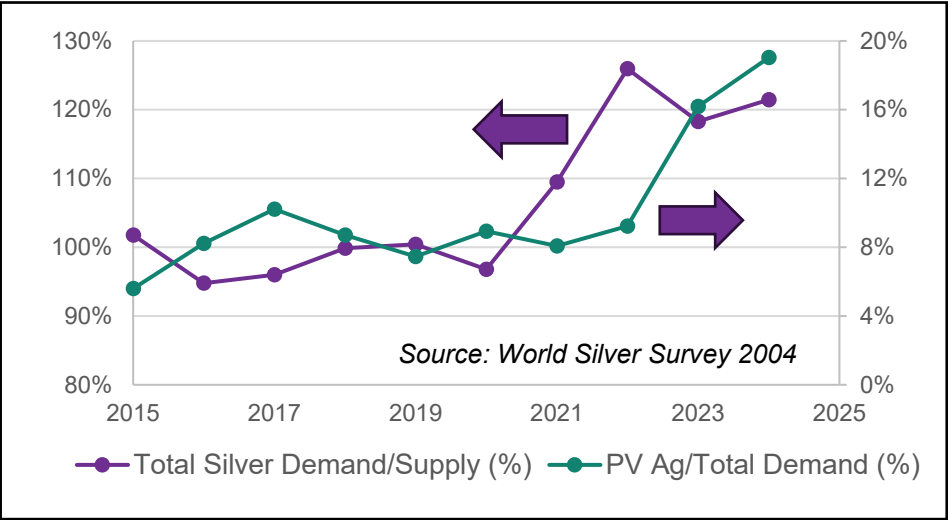
A Richter et al, Nature Energy, 2021, 6: 429-438  
R Peibst, et al. Prog Photovolt Res Appl. 2022: 1–14  
F Haase et al. Sol. Energy Mater. Sol. Cells, 2018, 186: 184-193

# Ag consumption nearly doubles with high efficiency cell technologies

## Trends in metallization silver consumption



# Reducing silver consumption is key to sustainability and growth

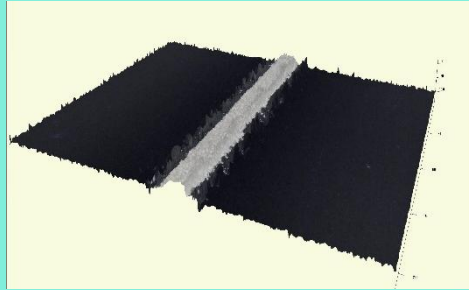


# Fine line is the mainstream solution to high efficiency and lower cost

**Fine line = Reduce Shading Loss + Lower Silver Paste Laydown**

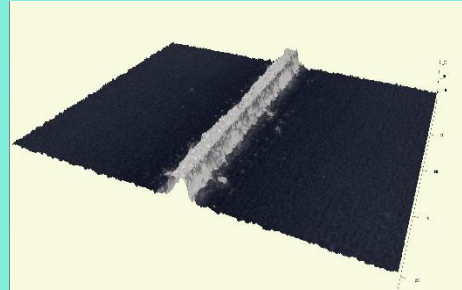
**High  
Temperature  
Air Firing**

Screen Printing



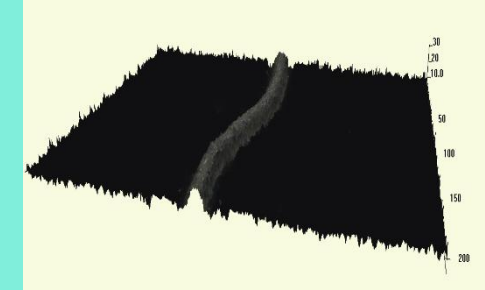
Current: 15~19um @ 8~11um FO  
Prospect: 13~17um @ 6~9um FO

Stencil Printing



Current: 12~15um @ 6~11um FO  
Prospect: 9~11um @ 4~6um FO

Pattern Transfer



Current: 10~12um @ 8~10um FO  
Prospect: 7~10um @ 6~8um FO

**Low  
Temperature  
Curing**

Screen Printing



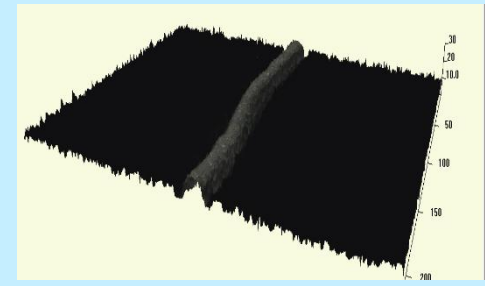
Current: 28~34um @ 16~17um FO  
Prospect: 24~30um @ 14~17um FO

Stencil Printing



Current: 22~28um @ 12~14um FO  
Prospect: 18~24um @ 10~12um FO

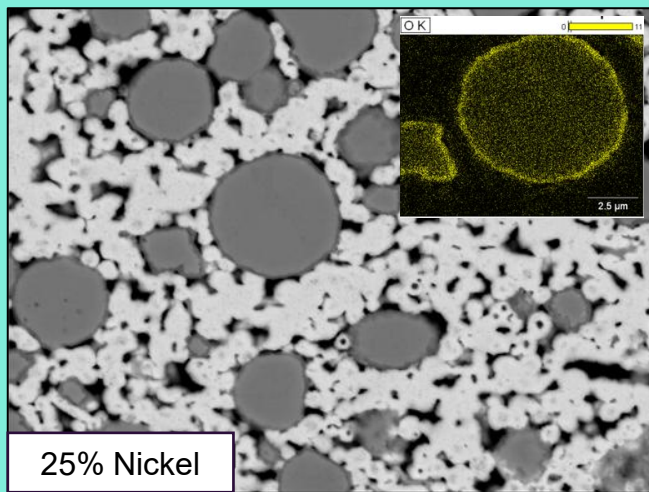
Pattern Transfer



Current: 17~19um @ 15~17um FO  
Prospect: 13~17um @ 12~15um FO

# Reduce silver content using base metals

High  
Temperature  
Air Firing

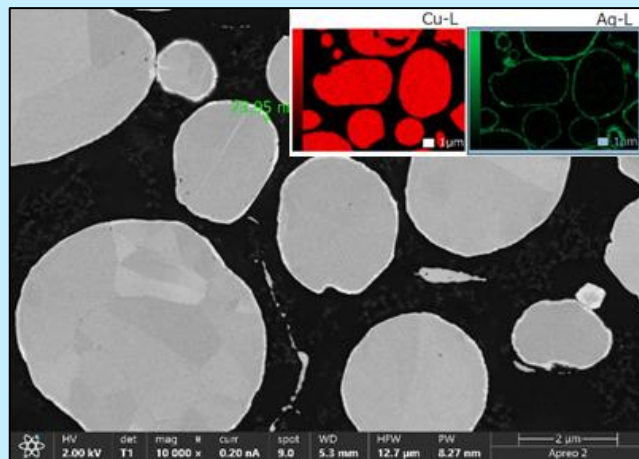


Customer Trials vs Silver Paste on TOPCon Rear Side

Sample	$\Delta V_{oc}$ (mV)	$\Delta FF$ (%)	$\Delta I_{sc}$ (mA)	$\Delta Eff$ (%)	Laydown (mg)
Customer A 5% Ni	+0.1	+0.1	-6	+0.02%	=
Customer B 10% Ni	-0.6	+0.14	-10	+0.01%	=

Combining nickel powder with customized glass frit design able to demonstrate competitive performance with significant silver saving

Low  
Temperature  
Curing

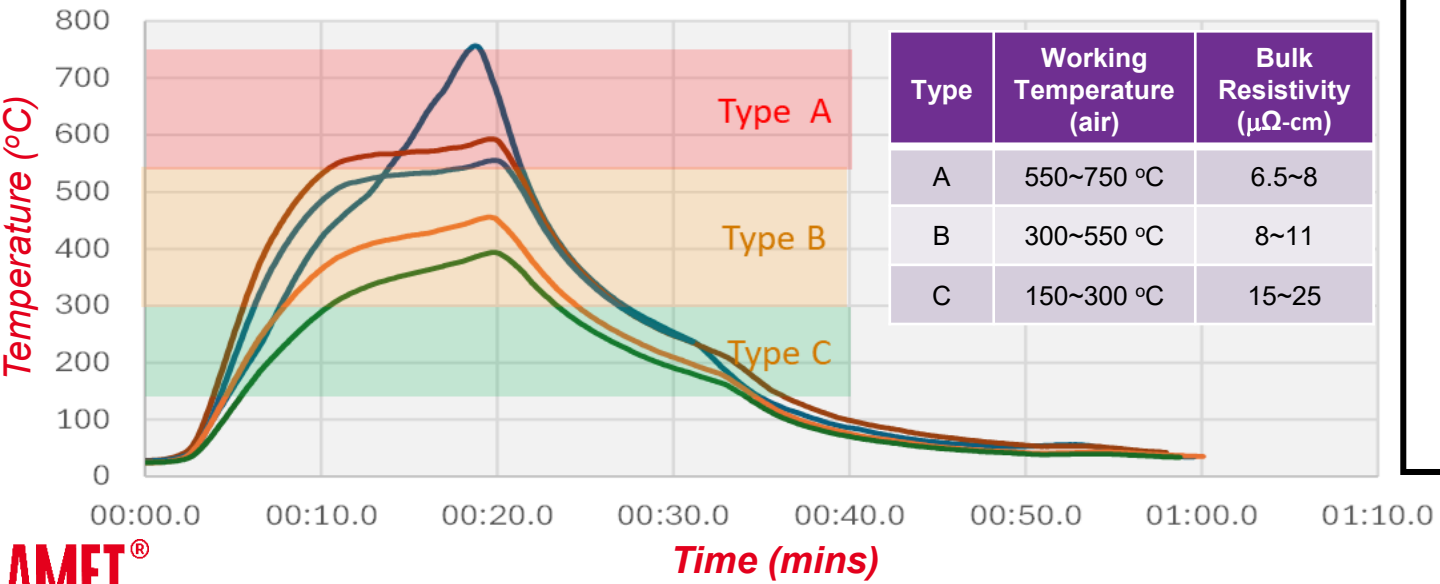
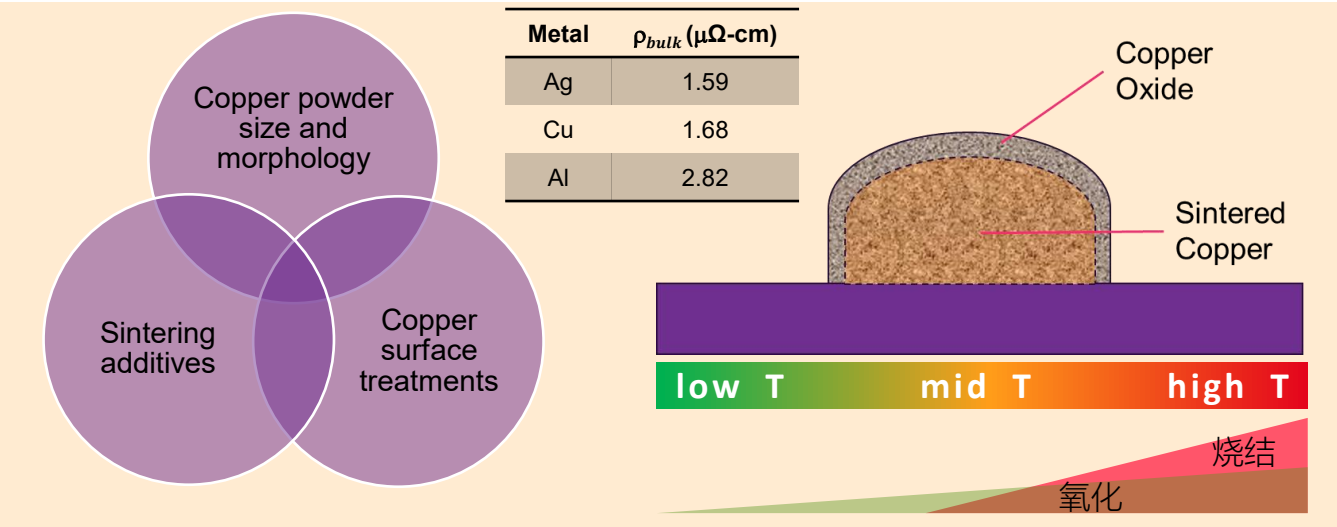


Solamet® PV43A Volume Resistivity with Different Ag Content

Product	Ag content	Resistivity $\mu\Omega \cdot cm$
PV43A-T6	40-50% Ag	5.5 – 6.0
PV43A-T7	30-40% Ag	6.0 - 6.5
PV43A-T8	20-30% Ag	6.5 – 8.0
PV43A-T9	10-20% Ag	8.0 – 13.0
PV43A-T9+	< 10% Ag	12.0-25.0

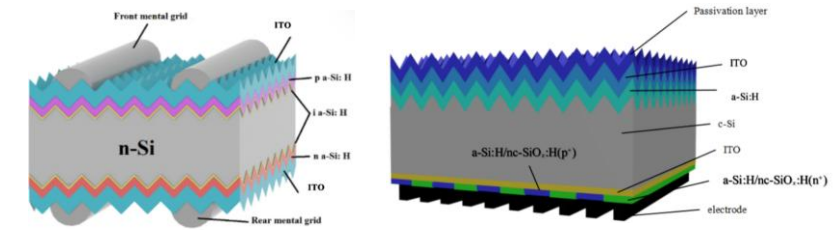


# Feasibility of silver-free copper metallization solutions



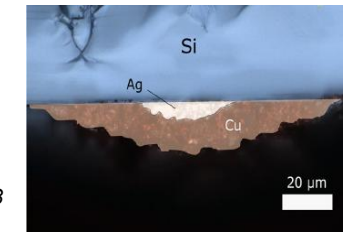
## Applications in high efficiency cell structures

1. Replace current Ag@Cu pastes for HJT and HBC cells

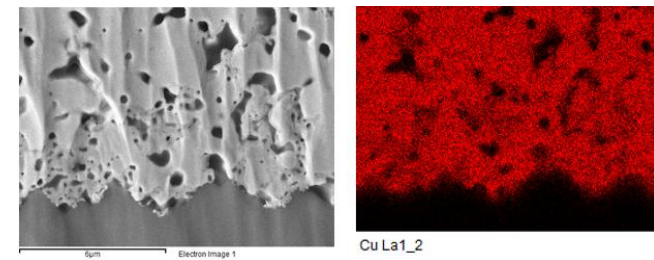


2. Two step using seed layer + low T copper paste for n-TOPCon and n-TBC

*Chen et al, Sol. RRL 2023*



3. One step co-firing using seed layer + copper paste for n-TOPCon and n-TBC





# Solamet Electronic Materials

DuPont™ Solamet® ➡ **SOLAMET® 索特**

- July 1, 2021, Jiangsu Solamet Electronic Materials Co., Ltd. acquired DuPont Solamet® metallization business, including all products, personnel, intellectual property, and assets worldwide
- Solamet is the industry innovation leader and holds the broadest portfolio and access to metallization paste intellectual properties

➤ Headquarters:

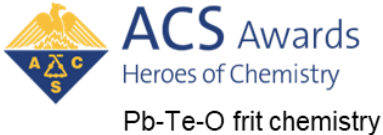
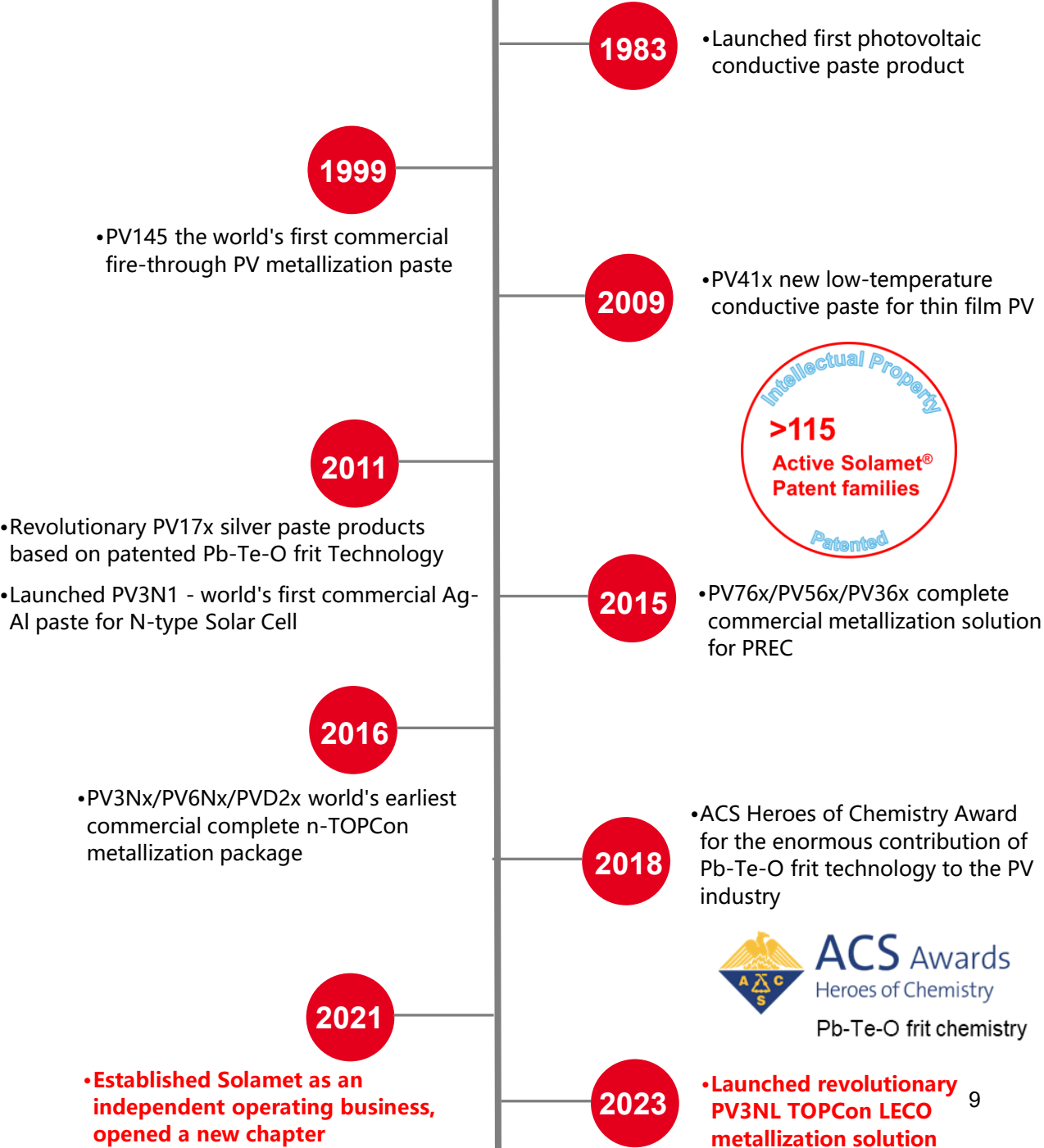
- Huzhou-Zhejiang (CN)
- Shanghai (CN)

➤ R&D and Technology Centers:

- Shanghai (CN)
- Taoyuan (TW)

➤ Manufacturing Sites:

- Dongguan (CN) t/yr
- Taoyuan (TW) → support customers with Taiwan made certification for US end market since 2023



# Closing Remarks

- High efficiency n-type solar cells have become mainstream in the market, however demand for silver paste already surpasses supply
- Reduction in mg Ag/watt is critical for sustainability and growth, requiring new breakthroughs in metallization technology
  - Ultra fine line technology for improving efficiency and reducing silver paste laydown
  - Reduced silver content metallization paste delivering at least comparable performances
  - Pure copper paste metallization paste towards a "silver free" future
- Solamet is committed to continue to invest and deliver innovations in metallization technology to drive higher efficiency and lower cost